AS159

*Product Description:*

AS159 is a high strength, fast curing, acetoxy silicone RTV adhesive rubber developed for applications requiring fast development of physical properties and excellent adhesion. AS159 is a 1 part high temperature silicone that when cured resists weathering, ozone, moisture and UV. AS159 works well in manual and automatic dispensing equipment.

*Product Features:*

- Fast Room Temperature Cure
- Thixotropic paste
- Excellent unprimed adhesion to plastic, metal glass
- Heat accelerated instant cure capability

*Heat Accelerated Curing:*

Typical utilization involves dispensing in open air and ambient humidity to result in a high strength adhesive rubber. However, cure speed can be accelerated with hot air to nearly instant cures exhibiting very fast adhesion. A 1 minute hot air stream exposure, followed by a 1 minute cool down in a humid environment, results in a cured elastomer condition exhibiting outstanding adhesion.

*Replacement For:*

GE 159, 106 and Dow DC736. Tested and conforms to requirements of MIL-A-46106 Type I Group III material.

*Packaging:*

Available in standard 3 oz. tubes and 10.3 oz. cartridges. Other size packaging available upon request.

*Shelf-life:*

Sealed containers 1 year from date of shipment when stored in a cool dry area below 70°F

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**High Strength Fast Cure Adhesive Sealant**

*Typical Properties:*

**UNCURED**

- Color: Red
- Viscosity, cps 500,000
- Specific Gravity 1.14
- Consistency Thixotropic paste
- Working time, mins. @ R.T. 4
- Tack Free Time, mins. @ R.T. 12
- Application Rate, 90 PSI, g/min. 250
- Solids 98%

**CURED – ROOM TEMPERATURE**

Cured – 72 hrs. @ R.T.

- Tensile Strength, PSI 750
- Elongation, % 850
- Durometer, Shore A 38
- Peel Strength, PPI 50
- Tear Strength, PLI 100
- Lap Shear Strength, PSI 330

**Electrical**

- Dielectric Strength, v/mil >500
- Dielectric Constant 2.8
- Dissipation Factor 0.001
- Volume Resistivity, ohm/cm 2.0 x 10^14

**Thermal**

- Brittle Point, °F (°C) -68 (-55)
- Maximum Continuous Operating Temperature, °F (°C) 572(300)
- Thermal Conductivity Btu/hr/ft², °F/ft 0.0005
- Coefficient of Expansion in/in/°F 20 x 10^{-5}
Application Instruction Sheet
for
AS157 and AS159

Clean surface and dry thoroughly. If using the optional “Tube Nozzle”, cut to desired bead size. Push sealant ahead by squeezing tube for uniform bead. The paste-like consistency makes it easy to be tooled using a spatula or wooden paddle. Tooling time, approximately 5 minutes at Room Temperature. TACK FREE approximately 20 minutes at Room Temperature. Normal Room Temperature cure time is 24 hours. Length of time for a full cure depends on thickness of application and other factors including temperature and humidity. Accelerated cure may be achieved using hot air. Thin bond line sections can be heat accelerated cured using a 1 minute hot air stream exposure. Test the exposure time on a sample prior to final application.

Primerless adhesion too many metals including aluminum, stainless steel, steel, glass, ceramics and many rigid plastics. Not for use on stovepipes, fireplaces or underwater. Not for use in delicate electric or electronic applications. For industrial use only. KEEP OF REACH OF CHILDREN.

FAA PMA Approved Products
Approved Eligibility for Pratt & Whitney, Rolls Royce, Canadair and Boeing
ALL MODELS